

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: SHIBATA, AKIJI , et al.

Serial No.: 10/797,003

Filed: 3/11/2004

Title: MOLD DIE AND METHOD FOR MANUFACTURING
SEMICONDUCTOR DEVICE USING THE SAME

Art Unit: 2814

Examiner: 503.43552X00

INFORMATION DISCLOSURE STATEMENT
UNDER 37 CFR 1.97 & 1.98

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

October 25, 2007

Sir:

In the matter of the above-identified application, applicants are submitting herewith a copy of a communication from a foreign patent office in a counterpart foreign application and copies of the documents listed, other than the U.S. documents, in the attached form equivalent to Form PTO/SB/08A for the Examiner's consideration.

This information disclosure statement is being submitted before the mailing of a first office action after the filing of a request for continued examination under 37 CFR 1.114.

To the extent the documents listed on the attached form equivalent to Form PTO/SB/08A or PTO/SB/08B are not in the English language, the requirement of 37 CFR 1.98(a)(3) for a concise explanation of the relevance is satisfied by an English language version or translation of the foreign patent office report citing the documents.

It is respectfully requested that this information disclosure statement be considered by the Examiner.

Please charge any shortage in the fees due in connection with the filing of this paper, including excess claim fees, to Deposit Account No. 01-2135 (503.43552X00), and please credit any excess fees to such deposit account.

Respectfully submitted,

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